

**PATENT ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT								
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT								
<b>CONVEYING PARTY DATA</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Dou Ker</td> <td>05/21/2007</td> </tr> <tr> <td>Yuan-Wen Hsiao</td> <td>05/21/2007</td> </tr> <tr> <td>Yuh-Kuang Tseng</td> <td>05/21/2007</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Dou Ker	05/21/2007	Yuan-Wen Hsiao	05/21/2007	Yuh-Kuang Tseng	05/21/2007
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Ming-Dou Ker	05/21/2007								
Yuan-Wen Hsiao	05/21/2007								
Yuh-Kuang Tseng	05/21/2007								
<b>RECEIVING PARTY DATA</b>									
<b>Name:</b>	Faraday Technology Corp.								
<b>Street Address:</b>	No.5, Li-Hsin Road 3, Science-Based Industrial Park								
<b>City:</b>	Hsin-Chu City								
<b>State/Country:</b>	TAIWAN								
<b>PROPERTY NUMBERS Total: 1</b>									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11753567</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11753567				
Property Type	Number								
Application Number:	11753567								
<b>CORRESPONDENCE DATA</b>									
<b>Fax Number:</b>	(703)997-4517								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
<b>Phone:</b>	3027291562								
<b>Email:</b>	Patent.admin.uspto.cr@naipo.com								
<b>Correspondent Name:</b>	WINSTON HSU								
<b>Address Line 1:</b>	P.O.BOX 506								
<b>Address Line 4:</b>	Merrifield, VIRGINIA 22116								
<b>ATTORNEY DOCKET NUMBER:</b>	FTCP0110USA								
<b>NAME OF SUBMITTER:</b>	WINSTON HSU								
<b>Total Attachments: 2</b> source=FTCP0110USA0_A1_1_NP005#page1.tif source=FTCP0110USA0_A1_1_NP005#page2.tif									

CH \$40.00 11753567

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Docket No FICP0110USA

### ASSIGNMENT OF INVENTION

In consideration of the payment by ASSIGNEE to ASSIGNOR of the sum of One Dollar (\$1.00), the receipt of which is hereby acknowledged, and for other good and valuable consideration.

**ASSIGNOR(S) (Inventors):**

Name: Ming-Dou Ker Nationality: R.O.C.

Address: 4F-3, No. 3, Lane 200, Bao-Shan Rd, Hsin-Chu City, Taiwan, R.O.C.

Name: Yuan-Wen Hsiao Nationality: R.O.C.

Address: No.7, Lane 82, Mingde St., South District, Tai-Chung City, Taiwan, R.O.C.

Name: Yuh-Kuang I seng Nationality: R.O.C.

Address: No. 12, Alley 15, Lane 20, Guangfu Rd., Bade City, Iao-Yuan Hsien, Taiwan, R.O.C.

Hereby sells, assigns and transfers to

**ASSIGNEE(S):**

Name: Faraday Technology Corp.

Address: No.5, Li-Hsin Road 3, Science-Based Industrial Park, Hsin-Chu City 300, Taiwan, R.O.C.

and the successors and assignees of the ASSIGNEE the entire right, title, and interest in and to any and all improvements which are disclosed in the invention entitled:

**"BONDING PAD STRUCTURE DISPOSED IN SEMICONDUCTOR DEVICE AND RELATED METHOD"**

Which is found in :

- (a) + U.S. patent application executed on even date
- (b) \_\_\_\_\_ U.S. patent application executed on \_\_\_\_\_
- (c) \_\_\_\_\_ U.S. application serial no \_\_\_\_\_
- (d) \_\_\_\_\_ patent no. \_\_\_\_\_ issued \_\_\_\_\_

NPO#FIC-P0110-USA:0  
CUSI#P2006-010-US-A

Assignment, Page 1 of 2

F#NPO-P0002E-US1  
DSB0-096U002389

**PATENT**  
**REEL: 019342 FRAME: 0345**

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and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof

ASSIGNOR hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment,

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to ASSIGNOR and will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof.

IN WITNESS WHEREOF, We have hereunto set hand and seal this MAY 21 2007 (Date of signing). (請發明人務必簽署上列日期。)

(Type name of inventor)

Signature of INVENTOR

Ming-Dou Ker

Ming-Dou Ker

Yuan-Wen Hsiao

Yuan-Wen Hsiao

Yuh-Kuang Tseng

Yuh-Kuang Tseng